

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-20. (Canceled)

21. (New) A light emitting device comprising:

a first lead;

a second lead;

a first semiconductor light emitting element mounted on said first lead;

a semiconductor element mounted on said first lead;

a first wire connecting said first semiconductor light emitting element and said second lead;

a second wire connecting said semiconductor element and said second lead;
and

a silicone resin provided to enclose said first semiconductor light emitting element, said semiconductor element, at least a part of said first lead, at least a part of said second lead, and said first and second wires, and second silicone resin having a hardness not lower than 50 in JISA value.

22. (New) A light emitting device according to claim 21, further comprising a third wire connecting said first semiconductor light emitting element and said first lead,

wherein said first lead having a slit formed therein between a portion where said first semiconductor light emitting element is mounted and a portion where said third wire is connected.

23. (New) A light emitting device according to claim 21, wherein said semiconductor element is a second semiconductor light emitting element.

24. (New) A light emitting device according to claim 23, wherein said first semiconductor light emitting element and said second semiconductor light emitting element are different in peak wavelength of light they emit.

25. (New) A light emitting device according to claim 21, wherein said silicone resin has a pre-curing viscosity in the range not lower than 100cp and not higher than 10000cp.

26. (New) A light emitting device according to claim 21, wherein said silicone resin has a convex surface configuration.

27. (New) A light emitting device according to claim 21, wherein said silicone resin has a hardness not higher than 90 in JISA value.

28. (New) A light emitting device according to claim 21, further comprising a fluorescent element which is included in said silicone resin, absorbs light emitted from said first semiconductor light emitting element and releases light of a peak